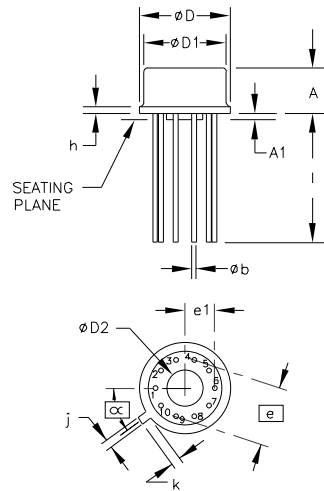


Package Number 007 - 10-Lead TO-100



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.165	.185	4.19	4.70	
A1	.010	.040	0.25	1.02	
b	.016	.021	0.41	0.53	
D	.335	.370	8.51	9.40	
D1	.305	.335	7.75	8.51	
D2	.120	.160	3.05	4.06	
e	.230	BASIC	5.84	BASIC	
e1	.110	.120	2.79	3.05	
h	.010	.040	0.25	1.02	
j	.028	.034	0.71	0.86	
k	.029	.045	0.74	1.14	
l	.500	--	12.70	--	
N	10	10			3
α	36°	BASIC	36°	BASIC	

NOTES:

- LEADS IN TRUE POSITION WITHIN .010" (0.25mm) R @ MMC AT SEATING PLANE.
- PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.
- N IS THE NUMBER OF TERMINAL POSITIONS.

PACKAGE NUMBER: ZZ007	REV.: B
JEDEC NUMBER: TO-100	

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